

# Series L3 / Ø 3mm

Colour: green

Sloan Part No.: L3-G51N-GUV



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## Electrical and Optical Characteristics (T<sub>A</sub> = 25°C)

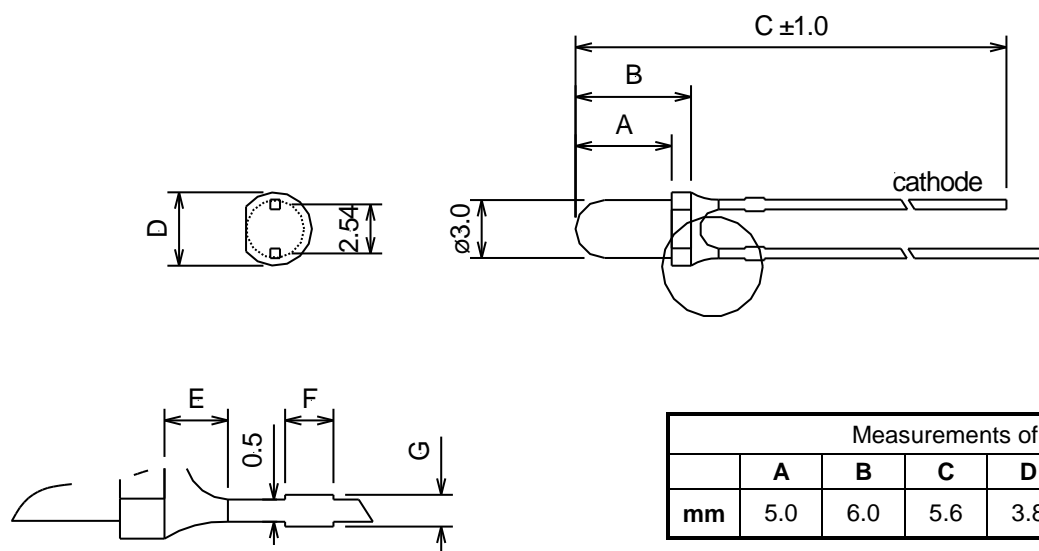
Chip			Lens	Absolute Maximum Rating				Electro-Optical-Data's at 20mA				Viewing Angle 2 θ ½ (deg)	
Emitted Colour	Peak Wavelength λ <sub>p</sub> (nm)	Dominant Wavelength λ <sub>p</sub> (nm)		Δλ (nm)	Pd (mW)	If (mA)	Peak If (mA)	Forward Voltage V <sub>f</sub> (V)		Luminous Intensity I <sub>v</sub> (mcd)			
			typ.					max.	min.	max.			
green	525	525	water clear	-	120	30	*100	3.6	4.0	7400		14000	30°

\*Peak Forward Current (1/10 Duty Cycle, 10ms Pulse Width)

## Absolute Maximum Ratings (T<sub>A</sub> = 25°C)

Reverse Voltage	5V
Reverse Current (V <sub>R</sub> = 5V)	≤50μA
Operating Temperature Range	- 30°C ~ +85°C
Storage Temperature Range	- 40°C ~ +100°C
Lead Soldering Temperature (3mm below the body)	300°C for 3 seconds

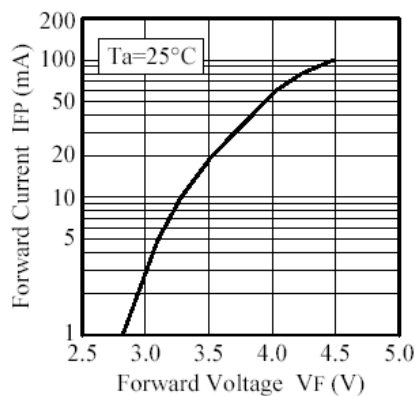
## Package Dimensions



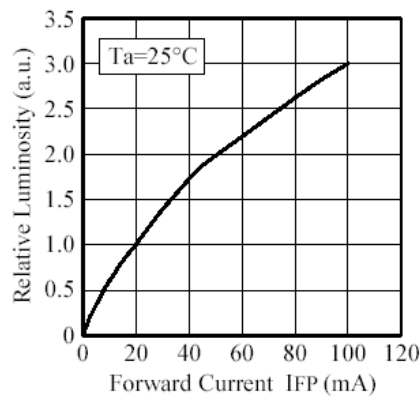
- All dimensions are in millimetres.
- Tolerance is ±0.25mm unless otherwise specified.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to change without notice.

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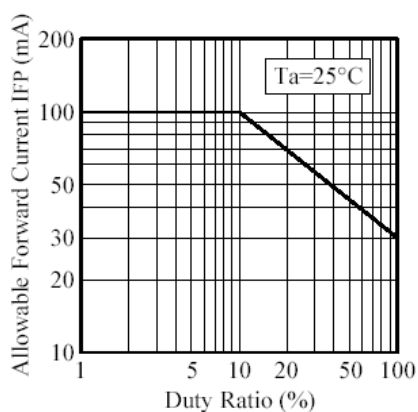
■ Forward Voltage vs. Forward Current



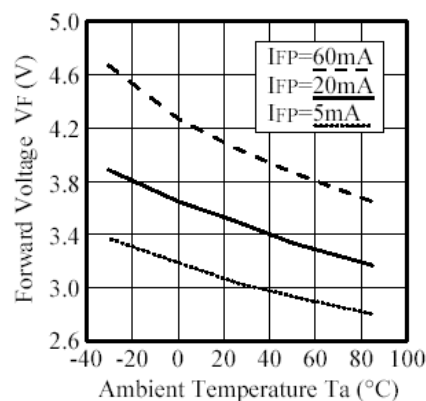
■ Forward Current vs. Relative Luminosity



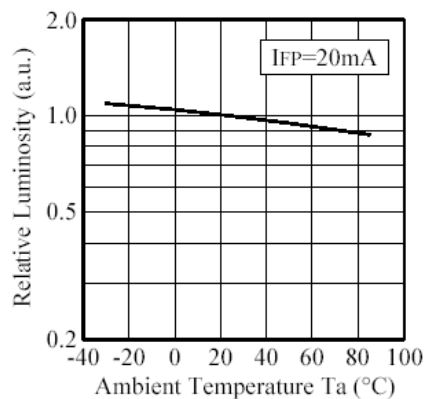
■ Duty Ratio vs. Allowable Forward Current



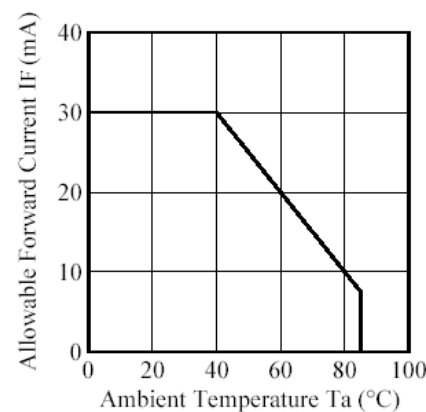
■ Ambient Temperature vs. Forward Voltage



■ Ambient Temperature vs. Relative Luminosity



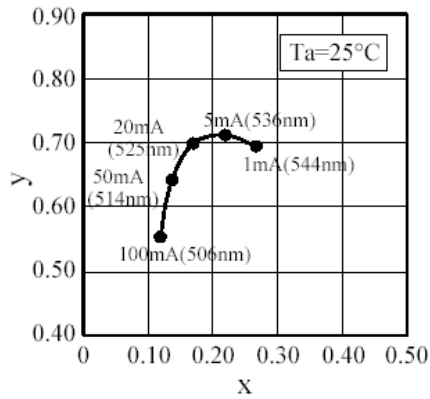
■ Ambient Temperature vs. Allowable Forward Current



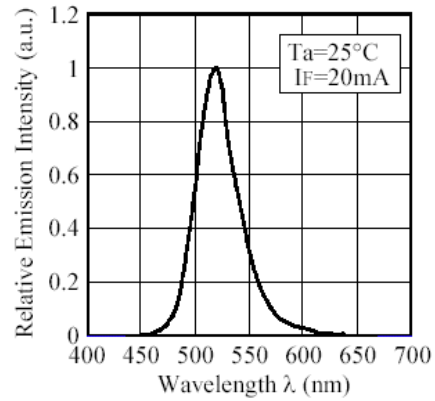
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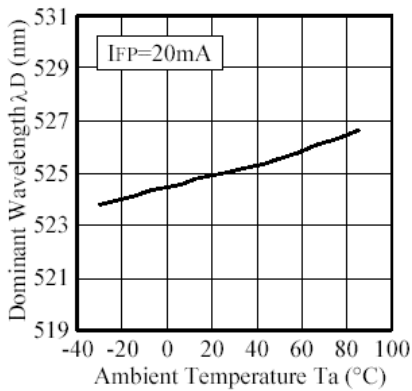
■ Forward Current vs. Chromaticity Coordinate ( $\lambda_D$ )



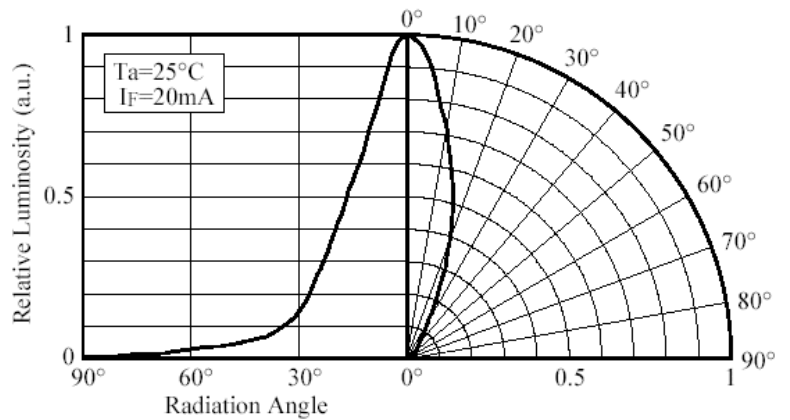
■ Spectrum



■ Ambient Temperature vs. Dominant Wavelength



■ Directivity



**Soldering:**

Dip Soldering		Soldering	
Pre-Heat	120°C Max.	Temperature	350°C Max.
Pre-Heat Time	60 seconds Max.	Soldering Time	3 seconds Max.
Solder Bath	260°C Max.	Position	No closer than 3 mm from the base of the epoxy bulb.
Temperature			
Dipping Time	10 seconds Max.		
Dipping Position	No lower than 3 mm from the base of the epoxy bulb.		